

HSEC8-08-01-L-DP-A



HSEC8-32-01-L-DP-A-WT

HSEC8-DP SERIES

FFERENTIAL PAIR EDGE CARD SU

SPECIFICATIONS

(0.80 mm) .0315"

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DP

Insulator Material:

Black Liquid Crystal Polymer Contact: Copper Alloy Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp:
Testing Now!
RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max

High-Speed Edge Rate® **Card Mates:**

(1.60 mm) .062" thick card

HSEC8

Contacts

APPLICATION



Designed for high-speed differential pair applications HIGH-SPEED CHANNEL PERFORMANCE PA M 4 HSEC8-DP

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

PLATING

OPTION

Optional weld tab available

ALSO AVAILABLE (MOQ Required)

- · Other platings
- · Other pin counts

Contact Samtec.

-08, -12, -16, -20, -32, -56 (Total Pairs)

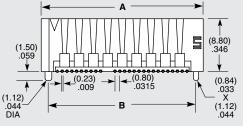
NO. OF

PAIRS

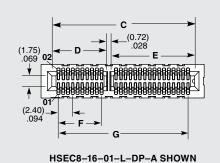
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-WT =Weld Tab

OPTION







NO. OF PAIRS	Α	В	С	D	E	F	G
-08	(17.40)	(15.00)	(14.20)	(4.34)	(9.14)	(2.40)	(12.00)
	.685	.591	.559	.171	.360	.094	.472
-12	(22.20)	(19.80)	(19.00)	(6.74)	(11.54)	(4.80)	(16.80)
	.874	.780	.748	.265	.454	.189	.661
-16	(27.00)	(24.60)	(23.80)	(9.14)	(13.94)	(7.20)	(21.60)
	1.063	.969	.937	.360	.549	.283	.850
-20	(31.80)	(29.40)	(28.60)	(11.54)	(16.34)	(9.60)	(26.40)
	1.252	1.157	1.126	.454	.643	.378	1.039
-32	(46.20)	(43.80)	(43.00)	(18.74)	(23.54)	(16.80)	(40.80)
	1.819	1.724	1.693	.738	.927	.661	1.606
-56	(75.00)	(72.60)	(71.80)	(33.14)	(37.94)	(31.20)	(69.60)
	2.953	2.858	2.827	1.305	1.494	1.228	2.740

Notes: Tape & Reel packaging and K-Dot are standard.

Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.